

Skyworks' Front-End Technology Supports Qualcomm's CDMA2000 and HSDPA Architectures

Family of Innovative Power Amplifiers Tailored to Select Qualcomm Chipsets

WOBURN, Mass.--(BUSINESS WIRE)--May 29, 2008--Skyworks Solutions, Inc. (NASDAQ: SWKS), an innovator of high performance analog and mixed signal semiconductors enabling mobile connectivity, today announced several new front-end solutions supporting Qualcomm's newest code division multiple access (CDMA) and HSDPA enhanced data for GSM evolution (HEDGE) reference platforms:

- The SKY77166 a 450 megahertz (MHz) power amplifier (PA) for CDMA handsets and wireless local loop (WLL) applications in a 4 x 4 mm package the smallest in the industry for applications in this frequency range. Skyworks is also working on defining a next-generation product that would drastically improve talk times in this growing market and will be designed to support certain Qualcomm chipsets.
- The SKY77183 (3 x 3 mm PA for the cellular band) and the SKY77184 (3 x 6 mm dual-band PA for cellular and PCS bands with integrated coupler) Skyworks' first PAs with full bypass mode. Routing the input signal directly from input to output bypasses the PA at low powers, enabling optimal operation at low output power levels and eliminating the need to supply current to the amplifier stages, resulting in significant savings in average battery current.
- The SKY77336 PAM designed in a compact 5 x 5 mm form factor for quad-band cellular handsets for GSM, GPRS and EDGE.

At a higher level, this is the first time Skyworks is working directly with Qualcomm on handset platforms targeted for nextgeneration multimode handset manufacturers.

"We are delighted to be working with Qualcomm on several exciting and upcoming handset platforms, particularly given their innovative radio architectures and technology leadership position," said David J. Aldrich, president and chief executive officer of Skyworks. "When combined with our core front-end capabilities, together we plan to deliver feature rich, best-in-class solutions to a number of the world's leading handset OEMs and smartphone suppliers."

The chipsets will support multiple wireless platform customers. The companies will manufacture these solutions, with mobile devices incorporating these designs available as early as later this year.

About HSDPA

High-speed downlink packet access (HSDPA) is a third generation (3G) mobile telephony communications protocol in the highspeed packet access (HSPA) family, which allows networks based on universal mobile telecommunications system (UMTS) to have higher data transfer speeds and capacity. Current HSDPA deployments support downlink speeds of 1.8, 3.6, 7.2 and 14.4 megabits (Mbit), with further speed increases planned in the near future.

About Skyworks

Skyworks Solutions, Inc. is an innovator of high performance analog and mixed signal semiconductors enabling mobile connectivity. The company's power amplifiers, front-end modules and direct conversion radios are at the heart of many of today's leading-edge multimedia handsets. Leveraging core technologies, Skyworks also offers a diverse portfolio of linear products that support automotive, broadband, cellular infrastructure, industrial and medical applications.

Headquartered in Woburn, Mass., Skyworks is worldwide with engineering, manufacturing, sales and service facilities throughout Asia, Europe and North America. For more information, please visit Skyworks' Web site at: www.skyworksinc.com.

Safe Harbor Statement

This news release includes "forward-looking statements" intended to qualify for the safe harbor from liability established by the Private Securities Litigation Reform Act of 1995. These forward-looking statements include information relating to future results and expectations of Skyworks (including certain projections and business trends). Forward-looking statements can often be identified by words such as "anticipates," "expects," "intends," "believes," "plans," "may," "will," "continue," similar expressions, and variations or negatives of these words. All such statements are subject to certain risks and uncertainties that could cause actual results to differ materially and adversely from those projected, and may affect our future operating results, financial position and cash flows.

These risks and uncertainties include, but are not limited to: global economic and market conditions, such as the cyclical nature of the semiconductor industry and the markets addressed by our, and our customers', products; our ability to develop, manufacture and market innovative products in a highly price competitive and rapidly changing technological environment; fluctuations in our manufacturing yields due to our complex and specialized manufacturing processes; our reliance on several key customers for a large percentage of our sales; fluctuations in the manufacturing yields of our third party semiconductor foundries and other problems or delays in the fabrication, assembly, testing or delivery of our products; the availability and pricing of third party semiconductor foundry, assembly and test capacity and raw materials; our ability to timely and accurately predict market requirements and evolving industry standards, and to identify opportunities in new markets; losses or curtailments of purchases or payments from key customers, or the timing of customer inventory adjustments; our ability to rapidly develop new products and avoid product obsolescence; our ability to retain, recruit and hire key executives, technical personnel and other employees in the positions and numbers, with the experience and capabilities, and at the compensation levels needed to implement our business and product plans; lengthy product development cycles that impact the timing of new product introductions; the timing, rescheduling or cancellation of significant customer orders and our ability, as well as the ability of our customers, to manage inventory; unfavorable changes in product mix; the guality of our products and any remediation costs; shorter than expected product life cycles; problems or delays that we may face in shifting our products to smaller geometry process technologies and in achieving higher levels of design integration; economic, social and political conditions in the countries in which we, our customers or our suppliers operate, including security and health risks, possible disruptions in transportation networks and fluctuations in foreign currency exchange rates; our ability to continue to grow and maintain an intellectual property portfolio and obtain needed licenses from third parties; and the uncertainties of litigation, including disputes over intellectual property, as well as other risks and uncertainties, including but not limited to those detailed from time to time in our filings with the Securities and Exchange Commission.

These forward-looking statements are made only as of the date hereof, and we undertake no obligation to update or revise the forward-looking statements, whether as a result of new information, future events or otherwise.

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